

# AN ESSENTIAL SELF-LEVELER WITH SPECIALTY CHARACTERISTICS

synthetic smoothing and leveling compound with many of the performance characteristics of a specialty player. Cover and level gypsum or concrete substrates, but also old ceramic tiles, cutback adhesives, OSB board, and plywood. Schönox AM Plus is only available from a limited number of participating distributors.



# SCHÖNOX AM PLUS

## THE HARDNESS AND STRENGTH NEEDED FOR SUBFLOOR FUNDAMENTALS

Schönox AM Plus does not shrink or expand with a compressive strength of 1,100 psi after one day and 4,800 psi after 28 days. Complete pours from 1/4 to 2-inch depths, handling rough, irregular subfloors with ease. Schönox AM Plus provides an option when subfloor basics need covering without higher performance characteristics.













### PRODUCT CHARACTERISTICS

- EMICODE EC 1: very low emission
- · Environmental and health benefits
- · Does not support mold growth
- · For interior use only
- · Self-leveling
- High hardness and strength
- · Suitable for underfloor heating systems
- · Layer-thickness above 1/4" up to 2"
- Pumpable
- Very low shrinkage
- · Free of cracks even in higher thicknesses
- · Suitable for castor wheel loadings
- Tested in accordance with ASTM C1708

#### RECOMMENDED APPLICATION DETAILS

Schönox AM Plus is suitable for leveling of:

- Gypsum substrates
- · Concrete, cement substrates
- · Old substrates such as ceramic tiles old. water-resistant adhesive residues
- OSB board, plywood (well screwed down and / or bonded prior to install of flexible coverings

#### **PRIMING**

- · Porous substrates such as concrete, cement substrates: prime with Schönox VD (1:3) or KH Fix
- Non porous, smooth, sound substrates such as ceramic tiles, old water-resistant adhesive residues (removed as far as possible), OSB board, and plywood (well screwed down and / or bonded): prime with Schönox SHP
- Gypsum substrates (sanded and vacuumed): prime with Schönox KH Fix

#### MIXING RATIO

- Mix each 25 kg / 55 lb. bag with 4.0 liters / 4.2 quarts of water
- · Do not overwater! Foam while mixing, or settling of the sand aggregate while placing, indicates overwatering.

#### RECOMMENDED WORKING METHOD

- · Adequate ventilation is essential when Schönox AM PLUS is being worked to ensure faster drying.
- Using a clean mixing drum, add Schönox AM Plus to cold, clean water to form a homogeneous mixture. Mix thoroughly for approx. 3 minutes using a heavy-duty drill (min. 600 rpm) to obtain a lump-free mix. Then pour the mix and spread using a smoothing trowel. Even surfaces are easily achieved using a pin leveler. In higher thicknesses, using a spike roller is recommended.
- Contact to vertical structures should be avoided by installing Schönox Foamtape. Avoid direct contact to metallic constructions (e.g. heating pipes), which can lead to corrosion.
- If a second layer of leveling compound is to be applied, prime the first layer with Schönox KH Fix after drying. The maximum layer thickness must not be exceeded in case of two-layer applications. The second layer must not exceed the layer thickness of the first layer.
- Protect curing Schönox AM Plus layers from high ambient temperatures, direct sunlight and droughts.
- · Clean tools in water immediately.

### **TECHNICAL DATA**

- · Pot life: approx. 30 minutes
- · Ready for foot traffic: approx. 3 hours
- Ready for covering: after approx. 24 48 hours at 1/4"
- Working temperature: 41°F 90°F
- Coverage per unit: approx. 26 sq.ft. at 1/4" (depending on substrate conditions)
- · Compressive strength (ASTM C109):
- 4,800 psi / 30 N/mm<sup>2</sup> / 320 kg/cm<sup>2</sup> after
- 1,100 psi / 6 N/mm<sup>2</sup> / 60kg/cm<sup>2</sup> after 1 day
- · Flexural strength (ASTM C348): approx. 1,100 psi / 7 N/mm<sup>2</sup> after 28 days
- · Tensile strength (ASTM C1583) at 1/8": above 300 / 2 N/mm<sup>2</sup> psi after 3 days
- Initial Set (ASTM C191): approx. 160 minutes
- Final Set (ASTM C191): approx. 200 minutes
- · Cured density: 120 lbs. / cu.ft.
- Flammability (ASTM E84): Flame Spread 0; Smoke Development 0

All values are approximate, are subject to local climatic fluctuations based upon conditions at 70°F with atmosphere of less than 65 % relative humidity following the recommended mixing ratio. Do not install underlayment or topping before the substrate has dried thoroughly.

# LEED V4.1 ID+C, BD+C

Contributes to LEED v4.1 certification of projects in these categories:

- EQc2 3 points: Low-Emitting Materials
- MRc1 up to 2 points: Life-Cycle Impact Reduction
- MRc2 1 point: Environmental **Product Declaration**
- MRc3 1 point: Sourcing of Raw Materials
- MRc4 1 point: Material Ingredients

Refer to Technical Data Sheets for additional, current information. Available on the Schönox app and at hpsubfloors.com.









